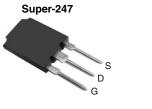
SiHS36N50D

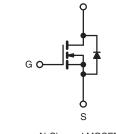




D Series Power MOSFET

PRODUCT SUMMA	RY	
V _{DS} (V) at T _J max.	550)
R _{DS(on)} max. at 25 °C (Ω)	$V_{GS} = 10 V$	0.130
Q _g max. (nC)	125	5
Q _{gs} (nC)	23	
Q _{gd} (nC)	37	
Configuration	Sing	le





N-Channel MOSFET

FEATURES

- Optimal Design
 - Low Area specific On-Resistance
 - Low Input Capacitance (Ciss)
 - Reduced Capacitive Switching Losses
 - High Body Diode Ruggedness
 - Avalanche Energy Rated (UIS)
- Optimal Efficiency and Operation
 - Low Cost
 - Simple Gate Drive Circuitry
 - Low Figure-Of-Merit (FOM): Ron x Qa
 - Fast Switching
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Consumer Electronics
 - Displays (LCD or Plasma TV
- Server and Telecom Power Supplies - SMPS
- Industrial
 - Welding, Induction Heating, Motor Drives
- Battery Chargers

ORDERING INFORMATION	
Package	Super-247
Lead (Pb)-free	SiHS36N50D-E3

PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		V _{DS}	500	
Gate-Source Voltage		N/	± 30	V
Gate-Source Voltage AC (f > 1 Hz)		V _{GS}	30	
Continuous Drain Current (T. 150 °C)	$T_{\rm C} = 25 ^{\circ}{\rm C}$		36	
Continuous Drain Current ($T_J = 150 \ ^{\circ}C$)	V_{GS} at 10 V $T_{C} = 100 \text{ °C}$	ID	23	А
Pulsed Drain Current ^a		I _{DM}	112	
Linear Derating Factor			3.6	W/°C
Single Pulse Avalanche Energy ^b		E _{AS}	332	mJ
Maximum Power Dissipation		PD	446	W
Operating Junction and Storage Temperature Range	e	T _J , T _{stg}	- 55 to + 150	°C
Drain-Source Voltage Slope	T _J = 125 °C	d\//d+	24	1//20
Reverse Diode dV/dt ^d		dV/dt	0.1	V/ns
Soldering Recommendations (Peak Temperature)	for 10 s		300 ^c	°C

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature. b. V_{DD} = 50 V, starting T_J = 25 °C, L = 2.3 mH, R_g = 25 Ω , I_{AS} = 17 A.

c. 1.6 mm from case.

d. $I_{SD} \leq I_D$, starting $T_J = 25$ °C.

RoHS

COMPLIANT

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SiHS36N50D

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THERMAL RESISTANCE RATII	163	1						
PARAMETER	SYMBOL	TYP.		MAX.		UNIT		
Maximum Junction-to-Ambient	R _{thJA}	-	- 40			°C/W		
Maximum Junction-to-Case (Drain)	R _{thJC}	- 0.28				- °C/W		
SPECIFICATIONS ($T_J = 25 \ ^{\circ}C$, u	nless otherwi	se noted)			I	T	1	1
PARAMETER	SYMBOL	TEST	T CONDIT	IONS	MIN.	TYP.	MAX.	UNI
Static								
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	= 0 V, I _D =	250 µA	500	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference	to 25 °C,	I _D = 250 μA	-	0.52	-	V/°C
Gate Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D =	250 µA	3.0	-	5.0	V
Gate-Source Leakage	I _{GSS}	,	$V_{GS} = \pm 30$	V	-	-	± 100	nA
	V _{DS} = 500 V, V _{GS} = 0 V		-	-	1			
Zero Gate Voltage Drain Current	I _{DSS}	_		√, T _J = 125 °C	-	-	10	μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V		_D = 18 A	-	0.105	0.130	Ω
Forward Transconductance ^a	9 _{fs}	V _{DS}	= 50 V, I _D	= 18 A	-	12.8	-	S
Dynamic							L	
Input Capacitance	C _{iss}		V _{GS} = 0 \	/	-	3233	-	
Output Capacitance	C _{oss}	$V_{\text{DS}} = 100 \text{ V},$ f = 1 MHz		-	285	-	pF	
Reverse Transfer Capacitance	C _{rss}			-	25	-		
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	V _{GS} = 0 V, V _{DS} = 0 V to 400 V		-	240	-		
Effective Output Capacitance, Time Related ^b	C _{o(tr)}	$V_{GS} = 0$ V	, v _{DS} = 0	v to 400 v	-	352	-	
Total Gate Charge	Qg				-	83	125	
Gate-Source Charge	Q _{gs}	$V_{GS} = 10 V$	I _D = 18	A, V _{DS} = 400 V	-	23	-	nC
Gate-Drain Charge	Q _{gd}				-	37	-	1
Turn-On Delay Time	t _{d(on)}				-	33	66	
Rise Time	t _r	V _{DD} =	= 400 V. I⊳	= 18 A.	-	89	134	
Turn-Off Delay Time	t _{d(off)}		V_{DD} = 400 V, I _D = 18 A, V _{GS} = 10 V, R _g = 9.1 Ω		-	79	119	ns
Fall Time	t _f			-	68	102		
Gate Input Resistance	Rg	f = 1 MHz, open drain		-	1.8	-	Ω	
Drain-Source Body Diode Characteristic	s							
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	36		
Pulsed Diode Forward Current	I _{SM}			-	-	144	- A	
Diode Forward Voltage	V _{SD}	T _J = 25 °C	C, I _S = 18 /	A, V _{GS} = 0 V	-	-	1.2	V
Reverse Recovery Time	t _{rr}		-		-	490	-	ns
Reverse Recovery Charge	Q _{rr}	$T_J = 25$	5 °C, I _F = I	_S = 18 A,	-	8.2	-	μC
Reverse Recovery Current	I _{RRM}	dl/dt = 1	100 A/µs,	v _R = 20 V	_	31	_	A

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

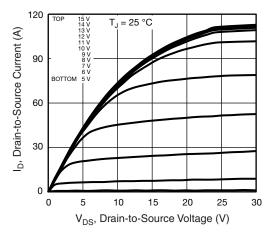


Fig. 1 - Typical Output Characteristics

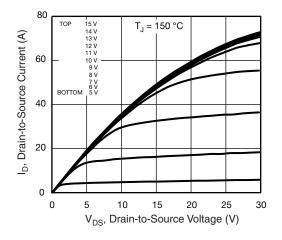


Fig. 2 - Typical Output Characteristics

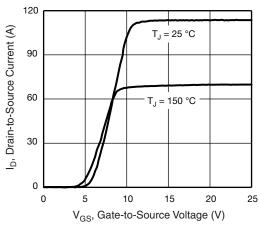


Fig. 3 - Typical Transfer Characteristics

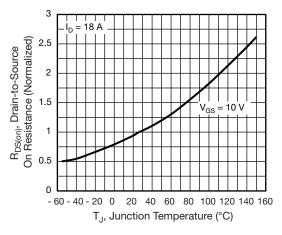


Fig. 4 - Normalized On-Resistance vs. Temperature

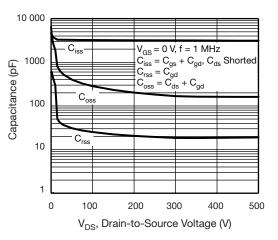


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

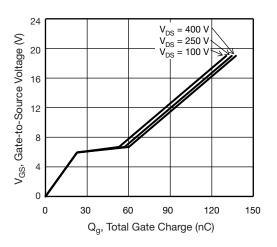


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

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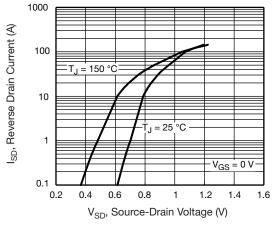
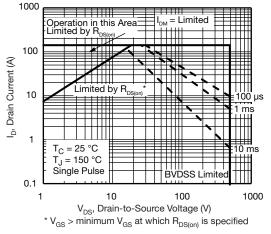
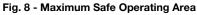


Fig. 7 - Typical Source-Drain Diode Forward Voltage





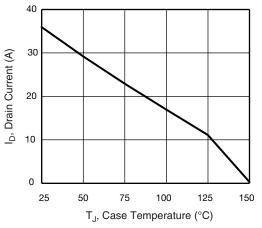


Fig. 9 - Maximum Drain Current vs. Case Temperature

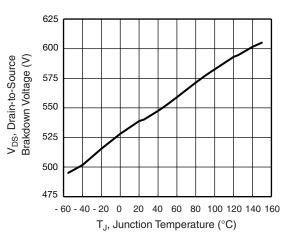
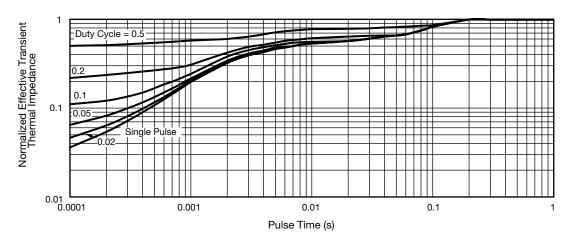


Fig. 10 - Temperature vs. Drain-to-Source Voltage





S12-1457-Rev. A, 18-Jun-12

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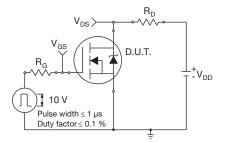


Fig. 12 - Switching Time Test Circuit

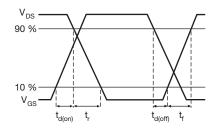


Fig. 13 - Switching Time Waveforms

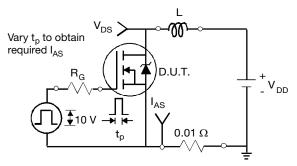


Fig. 14 - Unclamped Inductive Test Circuit

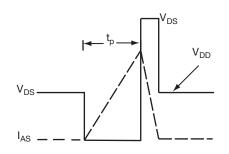


Fig. 15 - Unclamped Inductive Waveforms

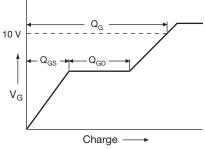


Fig. 16 - Basic Gate Charge Waveform

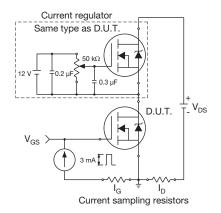


Fig. 17 - Gate Charge Test Circuit

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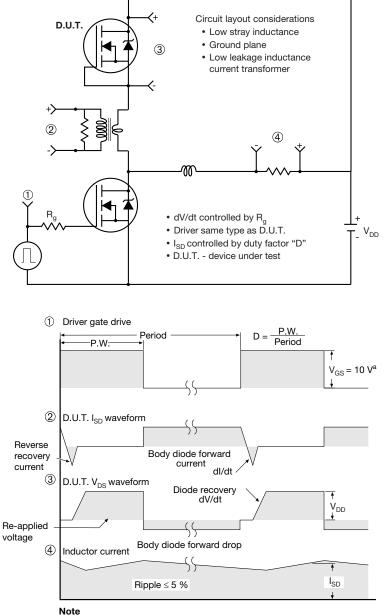
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Peak Diode Recovery dV/dt Test Circuit



a. $V_{GS} = 5$ V for logic level devices

Fig. 18 - For N-Channel

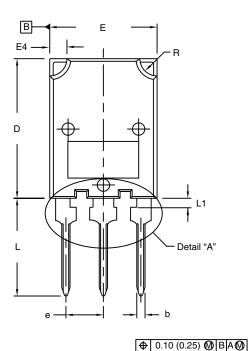
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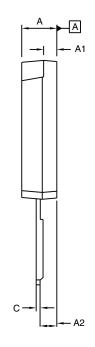
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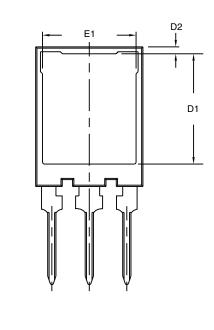
TO-274AA (HIGH VOLTAGE)

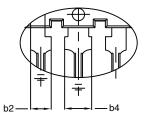


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Lead Tip









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	INC	HES		MILLIN	IETERS	INC
	MIN.	MAX.	DIM.	MIN.	MAX.	MIN.
	0.185	0.209	D1	15.50	16.10	0.610
	0.059	0.098	D2	0.70	1.30	0.028
	0.089	0.104	Е	15.10	16.10	0.594
	0.051	0.063	E1	13.30	13.90	0.524
	0.071	0.087	е	5.45	BSC	0.215
	0.118	0.128	L	13.70	14.70	0.539
	0.031	0.047	L1	1.00	1.60	0.039
	0.780	0.819	R	2.00	3.00	0.079

Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.

2. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outer extremes of the plastic body.

3. Outline conforms to JEDEC outline to TO-274AA.

MILLIMETERS

MAX.

5.30

2.50

2.65

1.60

2.20

3.25

1.20

20.80

MIN.

4.70

1.50

2.25

1.30

1.80

3.00

0.80

19.80

ECN: S-82247-Rev. A, 06-Oct-08

5

DIM.

A A1

A2

b

b2

b4

С

D

DWG: 5975

MAX.

0.634

0.051

0.634

0.547

0.579

0.063

0.118



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